RL-SQC-303 Rev 1.0

Printed Circuit Board Assembly (PCBA) Requirements – A

DOCUMENT PROPERTIES

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<tr>
<th>Document Type</th>
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DOCUMENT APPROVAL

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<tr>
<th>Author</th>
<th>Reviewer</th>
<th>Approver</th>
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<td>Released</td>
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1. Printed Circuit Board Assembly (PCBA) Data Package
   b. All manufacturer reports/results.
      i. The following shall be provided if the PCB was produced or
         procured by the PCBA subcontractor.
         1. The PCBA manufacturer shall include the items listed
            below:
            a. Micro Sections
               i. Final micro-sections coupons for both A
                  and B or A/B coupons shall be submitted
to Rocket Lab.
               ii. Micro-Section Analysis Report for both A
                  and B or A/B coupons shall be submitted
to Rocket Lab.
               iii. Coupons shall reflect coupon design in
                    IPC-2221 and the specified finished PCB
                    characteristics.
            b. If applicable, a complete list of the test results
               performed at the bare-board level or on the
               unpotted and potted
               harnesses.
            c. Results of ionic contamination testing
            d. All deviation and waiver reports, including all
               MRB actions taken on the PCBs or
               materials.
            e. All raw material reports and supplier
               certifications, if any
      c. The PCBA Data Package shall comprise the following document:
         i. As Built List (ABL)
            1. Part number and Lot or Date code information for all
               components shall be recorded to the Reference
               Designator of the PCBA
         ii. Material certificates
            1. Material used shall be traceable to the manufacturer’s
               lot number through date code and serial number
         iii. List of Assembly Materials (solder, ink, wire, flux, etc.)
            1. Lot and expiration date records shall be kept and
               provided upon request of Rocket Lab
         iv. Assembly Documents
            v. If applicable, a complete shortage list (parts and/or activities)
            vi. Deviations from drawings and parts lists and objective
               evidence for the approval
            vii. Copies of all redlined drawings and parts lists
            viii. Copies of all Non-Conformance reports if the resulting
                 disposition was Rework, Repair, or Use As Is
            ix. Evidence of approval from Rocket Lab for all non-
                conformances with disposition of Use As Is and/or Repair
            x. Rework documentation
            xi. Surface Mount Process Reflow Profile
            xii. X-Ray Images of CGA, BGA and BTC components
            xiii. X-Ray radiation dose experienced by the PCBA
            xiv. High resolution photo documentation of all sides of the
                 completed PCBA
            xv. If required, documentation for PCB or Component bake out
xvi. Unless otherwise specified, Flying Probe Data shall be submitted as part of the PCBA Data Package

2. Handling and Packaging
   a. Handling shall be in compliance with the requirements documented in appendix B of IPC-A-610
   b. Unless otherwise specified in the drawing, PCBAs shall be packed individually in static shielding packaging.
   c. External packaging shall protect the PCBAs from movement, shock events and physical damage during shipping and handling.
   d. Sealed bags containing PCBAs shall be wrapped in anti-static foam, bubble wrap, or other suitable static dissipative cushioning material.
   e. External packing shall be chosen to prevent tears, puncture opening, and/or other discrepancies upon receipt.

3. Polymeric Applications
   a. All polymeric Applications shall meet the requirements of NASA-STD-8739.1
Legal Warning

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